24 🛮 V_{CC}

23 Y1

22 Y2

21 Y3

18 Y6

16**∏** Y8

15 Y9

14 ¶ Y10

13 OE2

20 Y4 19 Y5

17 | Y7

DW OR NT PACKAGE

(TOP VIEW)

OE1

A1 🛮 2

А3

A4 🛮 5

A5 🛮 6

A6

A7 | 8

A8 🛮 9

A9 [] 10 A10 [] 11

GND 12

A2 | 3

[] 4

- Functionally Equivalent to AMD's AM29827 and AM29828
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- pnp Inputs Reduce dc Loading
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)
- Power-Up High-Impedance State
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (NT) 300-mil DIPs

description

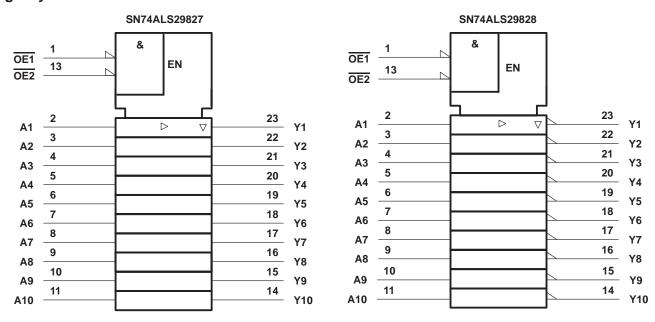
These 10-bit buffers and bus drivers provide high-performance bus interface for wide data paths or buses carrying parity.

The 3-state control gate is a 2-input NOR such that if either output-enable (OE1 or OE2) input is high, all ten outputs are in the high-impedance state.

The SN74ALS29827 provides true data and the SN74ALS29828 provides inverted data at their respective outputs.

The SN74ALS29827 and SN74ALS29828 are characterized for operation from 0°C to 70°C.

logic symbols†

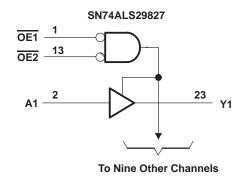


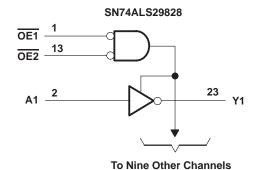
[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagrams (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I	5.5 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN74ALS29827 SN74ALS29828		UNIT	
		MIN	NOM	MAX	
Vcc	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
ІОН	High-level output current			-24	mA
l _{OL}	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

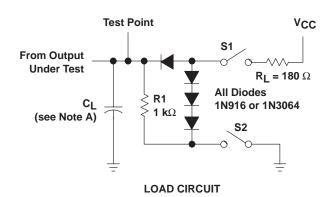
PARAMETER	TEST CON		SN74ALS29827 SN74ALS29828				
				TYP [†]	MAX		
VIK	$V_{CC} = 4.75 V,$	$I_{I} = -18 \text{ mA}$			-1.2	V	
Veri	V _{CC} = 4.75 V	$I_{OH} = -15 \text{ mA}$	2.4			V	
VOH		$I_{OH} = -24 \text{ mA}$	2]	
VOL	$V_{CC} = 4.75 V,$	$I_{OL} = 48 \text{ mA}$		0.35	0.5	V	
lozh	$V_{CC} = 5.25 V,$	V _O = 2.4 V			20	μΑ	
lozL	$V_{CC} = 5.25 V,$	V _O = 0.4 V			-20	μΑ	
ΙĮ	$V_{CC} = 5.25 V,$	V _I = 5.5 V			0.1	mA	
lін	$V_{CC} = 5.25 V,$	V _I = 2.7 V			20	μΑ	
I _{IL}	$V_{CC} = 5.25 V,$	V _I = 0.4 V			-0.1	mA	
los [‡]	$V_{CC} = 5.25 V,$	V _O = 0	-75		-250	mA	
Icc	V _{CC} = 5.25 V			25	40	mA	

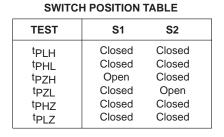
switching characteristics (see Figure 1)

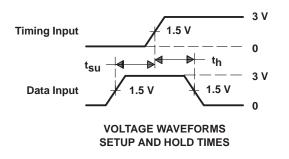
		TO (OUTPUT)	TEST CONDITIONS	V _{CC} = 4.75			
PARAMETER	FROM (INPUT)			SN74ALS29827	SN74ALS29828	UNIT	
	(01)	(0011 01)		MIN MAX	MIN MAX		
tPLH	А	V	O: 200 = E	15	14	ne	
tPHL	A	Y	$C_L = 300 pF$	15	14	ns	
t _{PLH}	А	V	0 50 - 5	8	7	no	
tPHL	A	Υ	$C_L = 50 pF$	8	7.5	ns	
^t PZH		V	0 000 - 5	20	20	ns	
tpzL	ŌĒ	Υ	C _L = 300 pF	23	23	113	
^t PZH	ŌĒ	V	0 50 = 5	15	15	ns	
t _{PZL}	OE	Y	$C_L = 50 pF$	15	15	119	
^t PHZ	^t PHZ	V	C _L = 50 pF	17	17	ns	
tPLZ	UE	Y		12	12		
^t PHZ	ŌĒ	Y	C 5 pE	9	9	ns	
^t PLZ	OE .	,	C _L = 5 pF	9	9		

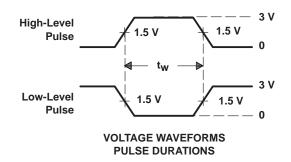
[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

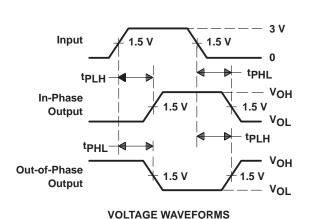
PARAMETER MEASUREMENT INFORMATION



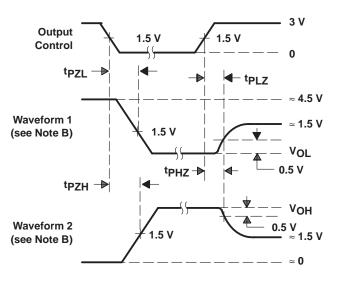








PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74ALS29827DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74ALS29827DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74ALS29827DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74ALS29827NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Purchase Samples
SN74ALS29827NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Purchase Samples
SN74ALS29828DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	Samples Not Available
SN74ALS29828DWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	Samples Not Available
SN74ALS29828NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	Samples Not Available

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

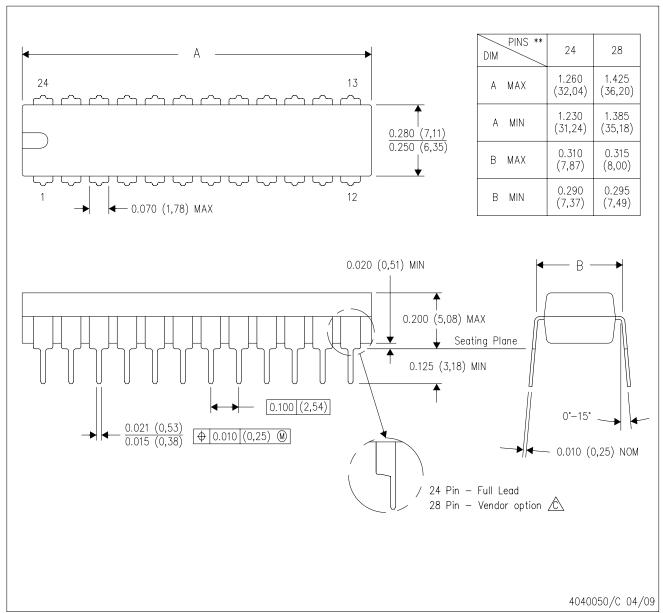
28-Aug-2010

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NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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